

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAC18SN03
Package Type :	PDFNWB5x6-8L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	3.92%
Lead Frame	Copper	7440-50-8	100.00%	39.38%
Die Attach	Tin	7440-31-5	4.70%	19.63%
	Lead	7439-92-1	85.00%	
	Silver	7440-22-4	2.30%	
	polyglycol	9038-95-3	5.00%	
	carboxlic	Trade secret	0.50%	
	proprietary	Trade secret	2.50%	
Wire1	copper	7440-50-8	99.990%	1.54%
	others	—	0.010%	
Wire2	Cu	7440-50-8	97.90%	2.19%
	Pd	7440-05-3	1.98%	
	Au	7440-57-5	0.12%	
Mold Compound	Quartz(SiO2)	14808-60-7	85.00%	29.61%
	epoxy resin	Trade secret	5.00%	
	epoxy,Cresol Novolac	29690-82-2	6.00%	
	Flame retardant	Trade secret	3.50%	
	Carbon Black	1333-86-4	0.50%	
Plating	Tin	7440-31-5	100.00%	3.73%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.